

Title (en)
CONNECTION HOUSING FOR AN ELECTRONIC COMPONENT

Title (de)
ANSCHLUSSGEHÄUSE FÜR EIN ELEKTRONISCHES BAUELEMENT

Title (fr)
BOITIER DE CONNEXION POUR UN COMPOSANT ELECTRONIQUE

Publication
EP 1382091 A2 20040121 (DE)

Application
EP 02732379 A 20020408

Priority

- DE 0201280 W 20020408
- DE 10120256 A 20010425

Abstract (en)
[origin: WO02089257A2] The connection housing comprises a base body (1) with lateral walls (2), which extend around the base body on the top and which enclose the component (6) to be inserted as well as inner contacts (8) that are arranged between the component and at least one lateral wall. Polymer protuberances (3) for forming outer contacts (4) are shaped onto the underside. The connection between the inner contacts (8) of the top and the outer contacts (4) of the underside is effected by micro-boreholes (11) that are located underneath the component (6) in the middle area of the base body (1). This results in the provision of a housing, which requires little space on a printed circuit board and which can be economically produced preferably while using laser structuring.

IPC 1-7
H01R 13/03; **H01L 23/13**; **H05K 3/34**

IPC 8 full level
H01L 23/13 (2006.01); **H01R 13/03** (2006.01); **H01L 23/04** (2006.01); **H03H 9/25** (2006.01); **H03H 9/64** (2006.01); **H05K 1/11** (2006.01); **H01L 23/055** (2006.01); **H05K 3/42** (2006.01)

CPC (source: EP KR US)
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C-Set (source: EP US)
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